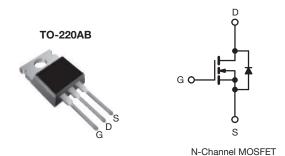
Vishay Siliconix

EL Series Power MOSFET



PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.155			
Q _g max. (nC)	82				
Q _{gs} (nC)	20				
Q _{gd} (nC)	13				
Configuration	Single				

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free and halogen-free	SiHP22N60AEL-GE3		

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	600	V	
Gate-source voltage			V_{GS}	± 30	V	
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	- I _D	21	А	
	V _{GS} at 10 V	T _C = 100 °C		13		
Pulsed drain current ^a			I _{DM}	48		
Linear derating factor				1.7	W/°C	
Single pulse avalanche energy ^b			E _{AS}	183	mJ	
Maximum power dissipation			P_D	208	W	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C		
Reverse diode dv/dt ^d			dv/dt	50	V/ns	
Soldering recommendations (peak temperature) ^c	For 10 s			260	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 3.6 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting $T_J = 25$ °C



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THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction-to-ambient	R _{thJA}	-	62	°C/W		
Maximum junction-to-case (drain)	R _{thJC}	-	0.6	C/VV		

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA		0.68	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		-	4.0	V
Out	I _{GSS}	,	$V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
Gate-source leakage		,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zava sata valtasa duais acurant		V _{DS} =	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C		-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 11 A	-	0.155	0.180	Ω
Forward transconductance	9 _{fs}	V _{DS} = 8 V, I _D = 11 A		-	16	-	S
Dynamic							
Input capacitance	C _{iss}	V _{GS} = 0 V,		-	1757	-	pF
Output capacitance	C _{oss}	Τ,	V _{GS} = 0 V, V _{DS} = 100 V,		74	-	
Reverse transfer capacitance	C _{rss}	f = 1 MHz		-	6	-	
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	48	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	257	-	
Total gate charge	Qg			-	41	82	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 11 \text{ A}, V_{DS} = 480 \text{ V}$		10	-	nC
Gate-drain charge	Q _{gd}	7			13	-	
Turn-on delay time	t _{d(on)}		$V_{DD} = 480 \text{ V}, I_{D} = 11 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		27	54	- ns
Rise time	t _r	V _{DD} =			24	48	
Turn-off delay time	t _{d(off)}	V _{GS} =			86	172	
Fall time	t _f			-	28	56	
Gate input resistance	Rg	f = 1 MHz, open drain		3.6	7.2	14.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET sym showing the	MOSFET symbol showing the		-	21	
Pulsed diode forward current	I _{SM}	integral reverse p - n junction diode		-	-	48	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 11 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	T _J = 25 °C, I _F = I _S = 11 A, di/dt = 100 A/μs, V _R = 400 V		-	285	570	ns
Reverse recovery charge	Q _{rr}			-	4.1	8.2	μC
Reverse recovery current	I _{RRM}			_	27	-	Α

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

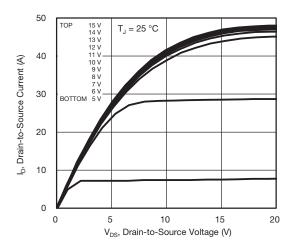


Fig. 1 - Typical Output Characteristics

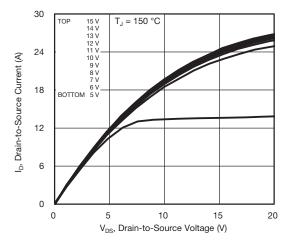


Fig. 2 - Typical Output Characteristics

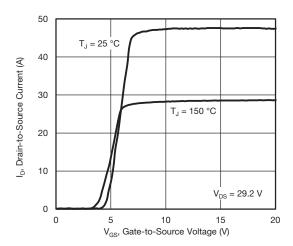


Fig. 3 - Typical Transfer Characteristics

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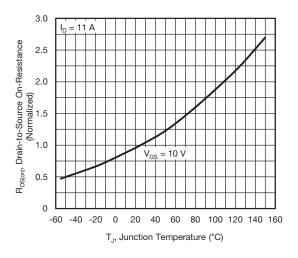


Fig. 4 - Normalized On-Resistance vs. Temperature

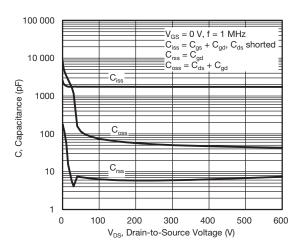


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

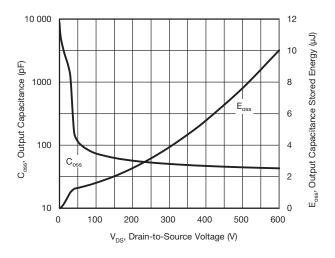


Fig. 6 - Coss and Eoss vs. VDS

3



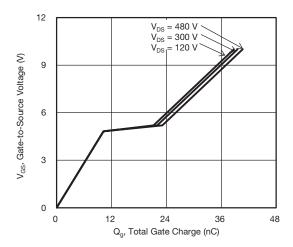


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

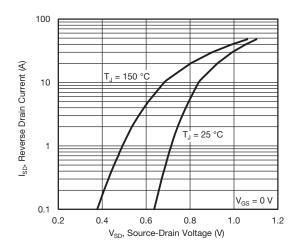


Fig. 8 - Typical Source-Drain Diode Forward Voltage

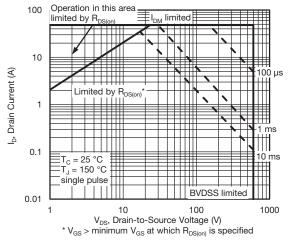


Fig. 9 - Maximum Safe Operating Area

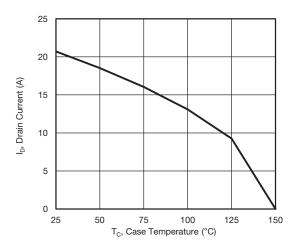


Fig. 10 - Maximum Drain Current vs. Case Temperature

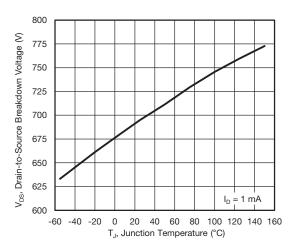


Fig. 11 - Temperature vs. Drain-to-Source Voltage



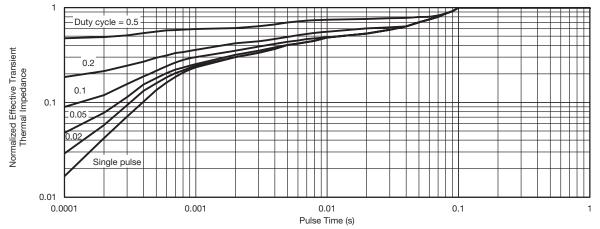


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

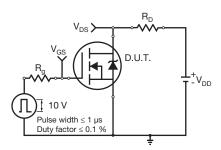


Fig. 13 - Switching Time Test Circuit

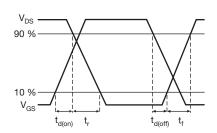


Fig. 14 - Switching Time Waveforms

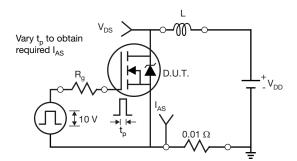


Fig. 15 - Unclamped Inductive Test Circuit

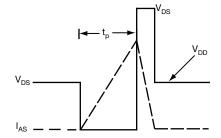


Fig. 16 - Unclamped Inductive Waveforms

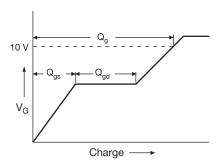


Fig. 17 - Basic Gate Charge Waveform

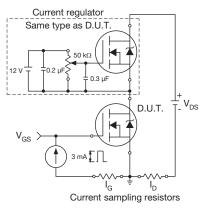
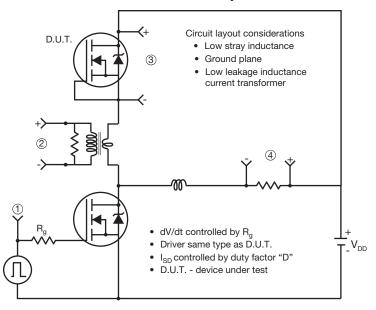


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



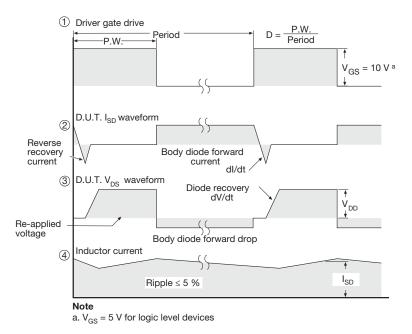


Fig. 19 - For N-Channel

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